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March 2007

74ABT245
Octal Bi-Directional Transceiver with 3-STATE Outputs

Features

■ Bidirectional non-inverting buffers
■ A and B output sink capability of 64mA, source capability of 32mA
■ Guaranteed output skew
■ Guaranteed multiple output switching specifications
■ Output switching specified for both 50pF and 250pF loads
■ Guaranteed simultaneous switching, noise level and dynamic threshold performance
■ Guaranteed latchup protection
■ High-impedance, glitch-free bus loading during entire power up and power down cycle
■ Nondestructive, hot-insertion capability
■ Disable time is less than enable time to avoid bus contention

General Description

The ABT245 contains eight non-inverting bidirectional buffers with 3-STATE outputs and is intended for bus-oriented applications. Current sinking capability is 64 mA on both the A and B ports. The Transmit/Receive (T/$\overline{R}$) input determines the direction of data flow through the bidirectional transceiver. Transmit (active HIGH) enables data from A Ports to B Ports; Receive (active LOW) enables data from B Ports to A Ports. The Output Enable input, when HIGH, disables both A and B ports by placing them in a HIGH Z condition.
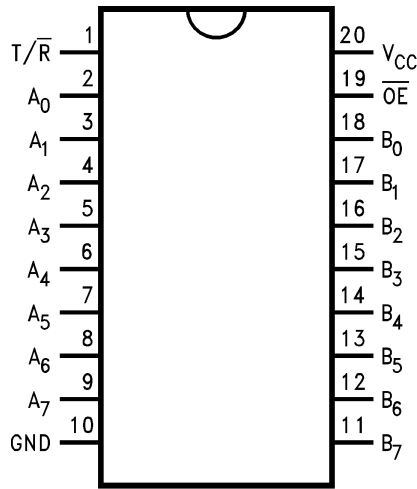
Ordering Information

Order Number	Package Number	Package Description
74ABT245CSC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74ABT245CSJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74ABT245CMSA	MSA20	20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide
74ABT245CMTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74ABT245CMTCX_NL[1]	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.
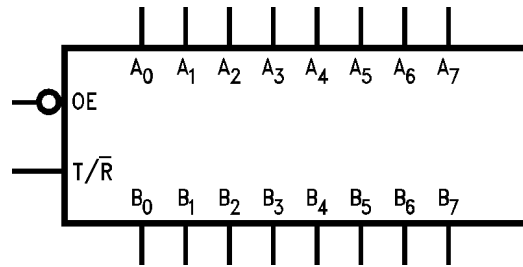Pb-Free package per JEDEC J-STD-020B.

Note:
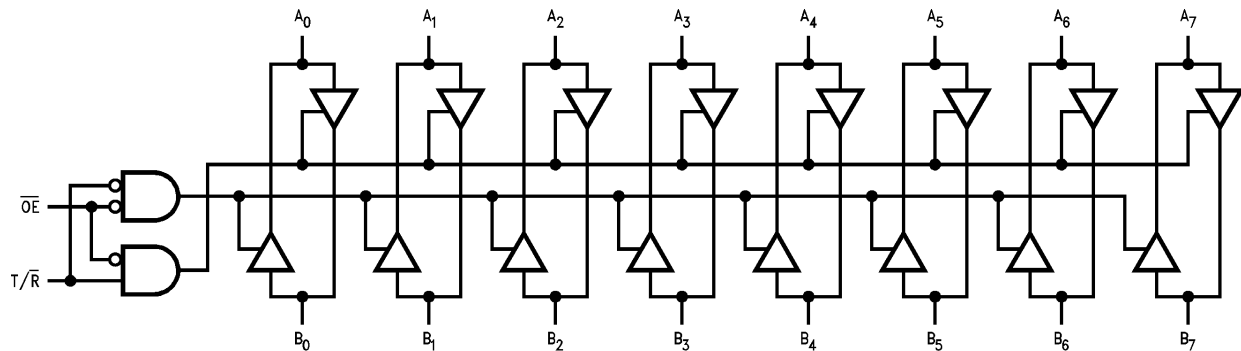1. Device available in Tape and Reel only.

Connection Diagram

Pin		Pin	
1	T/$\overline{R}$	20	V_{CC}
2	A_0	19	$\overline{OE}$
3	A_1	18	B_0
4	A_2	17	B_1
5	A_3	16	B_2
6	A_4	15	B_3
7	A_5	14	B_4
8	A_6	13	B_5
9	A_7	12	B_6
10	GND	11	B_7

Logic Symbol

Pin Descriptions

Pin Names	Description
$\overline{OE}$	Output Enable Input (Active LOW)
T/$\overline{R}$	Transmit/Receive Input
A_0–A_7	Side A Inputs or 3-STATE Outputs
B_0–B_7	Side B Inputs or 3-STATE Outputs

Truth Table

Inputs		
$\overline{OE}$	T/$\overline{R}$	Output
L	L	Bus B Data to Bus A
L	H	Bus A Data to Bus B
H	X	HIGH Z State

H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

Logic Diagram

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74ABT245 Octal Bi-Directional Transceiver with 3-STATE Outputs

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
T_{STG}	Storage Temperature	–65°C to +150°C
T_A	Ambient Temperature Under Bias	–55°C to +125°C
T_J	Junction Temperature Under Bias	–55°C to +150°C
V_{CC}	V_{CC} Pin Potential to Ground Pin	–0.5V to +7.0V
V_{IN}	Input Voltage[2]	–0.5V to +7.0V
I_{IN}	Input Current[2]	–30mA to +5.0mA

V_O	Voltage Applied to Any Output
	    Disabled or Power-off State
	    HIGH State
		–0.5V to 5.5V
		–0.5V to V_{CC}

	Current Applied to Output in LOW State	twice the rated I_{OL} (mA)
	DC Latchup Source Current	–500mA
	Over Voltage Latchup (I/O)	10V

Note:

2. Either voltage limit or current limit is sufficient to protect inputs.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
T_A	Free Air Ambient Temperature	–40°C to +85°C
V_{CC}	Supply Voltage	+4.5V to +5.5V

$\Delta V / \Delta t$	Minimum Input Edge Rate
	    Data Input
	    Enable Input
		50mV/ns
		20mV/ns

DC Electrical Characteristics

Symbol	Parameter		V_{CC}	Conditions	Min.	Typ.	Max.	Units
V_{IH}	Input HIGH Voltage			Recognized HIGH Signal	2.0			V
V_{IL}	Input LOW Voltage			Recognized LOW Signal			0.8	V
V_{CD}	Input Clamp Diode Voltage		Min.	$I_{IN} = -18$ mA ($\overline{OE}$, T/$\overline{R}$)			−1.2	V
V_{OH}	Output HIGH Voltage		Min.	$I_{OH} = -3$ mA (A_n, B_n)	2.5			V
			Min.	$I_{OH} = -32$ mA (A_n, B_n)	2.0			
V_{OL}	Output LOW Voltage		Min.	$I_{OL} = 64$ mA (A_n, B_n)			0.55	V
I_{IH}	Input HIGH Current		Max.	$V_{IN} = 2.7$V ($\overline{OE}$, T/$\overline{R}$)			1	µA
				$V_{IN} = V_{CC}$ ($\overline{OE}$, T/$\overline{R}$)			1	
I_{BVI}	Input HIGH Current Breakdown Test		Max.	$V_{IN} = 7.0$V ($\overline{OE}$, T/$\overline{R}$)			7	µA
I_{BVIT}	Input HIGH Current Breakdown Test (I/O)		Max.	$V_{IN} = 5.5$V (A_n, B_n)			100	µA
I_{IL}	Input LOW Current		Max.	$V_{IN} = 0.5$V ($\overline{OE}$, T/$\overline{R}$)			−1	µA
				$V_{IN} = 0.0$V ($\overline{OE}$, T/$\overline{R}$)			−1	
V_{ID}	Input Leakage Test		0.0	$I_{ID} = 1.9$ µA ($\overline{OE}$, T/$\overline{R}$), All Other Pins Grounded	4.75			V
$I_{IH} + I_{OZH}$	Output Leakage Current		0–5.5V	$V_{OUT} = 2.7$V (A_n, B_n), $\overline{OE} = 2.0$V			10	µA
$I_{IL} + I_{OZL}$	Output Leakage Current		0–5.5V	$V_{OUT} = 0.5$V (A_n, B_n), $\overline{OE} = 2.0$V			−10	µA
I_{OS}	Output Short-Circuit Current		Max.	$V_{OUT} = 0.0$V (A_n, B_n)	−100		−275	mA
I_{CEX}	Output HIGH Leakage Current		Max.	$V_{OUT} = V_{CC}$ (A_n, B_n)			50	µA
I_{ZZ}	Bus Drainage Test		0.0	$V_{OUT} = 5.5$V (A_n, B_n), All Others GND			100	µA
I_{CCH}	Power Supply Current		Max.	All Outputs HIGH			50	µA
I_{CCL}	Power Supply Current		Max.	All Outputs LOW			30	mA
I_{CCZ}	Power Supply Current		Max.	$\overline{OE} = V_{CC}$, T/$\overline{R}$ = GND or V_{CC}, All Other GND or V_{CC}			50	µA
I_{CCT}	Additional I_{CC}/Input	Outputs Enabled	Max.	$V_I = V_{CC} - 2.1$V			2.5	mA
		Outputs 3-STATE		$\overline{OE}$, T/$\overline{R}$ $V_I = V_{CC} - 2.1$V			2.5	mA
		Outputs 3-STATE		Data Input $V_I = V_{CC} - 2.1$V, All Others at V_{CC} or GND.			50	µA
I_{CCD}	Dynamic I_{CC} No Load		Max.	Outputs Open, $\overline{OE}$ = GND, T/$\overline{R}$ = GND or V_{CC}, One Bit Toggling, 50% Duty Cycle			0.1	mA/ MHz

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DC Electrical Characteristics

SOIC package.

Symbol	Parameter	V_{CC}	Conditions $C_L = 50$ pF, $R_L = 500\Omega$	Min.	Typ.	Max.	Units
V_{OLP}	Quiet Output Maximum Dynamic V_{OL}	5.0	$T_A = 25°C$[3]		0.7	1.0	V
V_{OLV}	Quiet Output Minimum Dynamic V_{OL}	5.0	$T_A = 25°C$[3]	−1.3	−1.0		V
V_{OHV}	Minimum HIGH Level Dynamic Output Voltage	5.0	$T_A = 25°C$[5]	2.7	3.1		V
V_{IHD}	Minimum HIGH Level Dynamic Input Voltage	5.0	$T_A = 25°C$[4]	2.0	1.7		V
V_{ILD}	Maximum LOW Level Dynamic Input Voltage	5.0	$T_A = 25°C$[4]		0.9	0.6	V

Notes:

3. Max number of outputs defined as (n). n-1 data inputs are driven 0V to 3V. One output at LOW. Guaranteed, but not tested.

4. Max number of data inputs (n) switching. n-1 inputs switching 0V to 3V. Input-under-test switching: 3V to threshold (V_{ILD}), 0V to threshold (V_{IHD}). Guaranteed, but not tested.

5. Max number of outputs defined as (n). n − 1 data inputs are driven 0V to 3V. One output HIGH. Guaranteed, but not tested.

AC Electrical Characteristics

SOIC and SSOP package.

Symbol	Parameter	$T_A = +25°C$, $V_{CC} = +5V$, $C_L = 50pF$			$T_A = −55°C$ to $+125°C$, $V_{CC} = 4.5V$ to $5.5V$, $C_L = 50pF$		$T_A = −40°C$ to $+85°C$, $V_{CC} = 4.5V$ to $5.5V$, $C_L = 50pF$		Units
		Min.	Typ.	Max.	Min.	Max.	Min.	Max.	
t_{PLH}	Propagation Delay, Data to Outputs	1.0	2.1	3.6	1.0	4.8	1.0	3.6	ns
t_{PHL}		1.0	2.4	3.6	1.0	4.8	1.0	3.6	
t_{PZH}	Output Enable Time	1.5	3.2	6.0	1.0	6.7	1.5	6.0	ns
t_{PZL}		1.5	3.7	6.0	2.0	7.5	1.5	6.0	
t_{PHZ}	Output Disable Time	1.0	3.6	6.1	1.7	7.4	1.0	6.1	ns
t_{PLZ}		1.0	3.3	5.6	1.7	6.5	1.0	5.6	

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Extended AC Electrical Characteristics

SOIC package.

Symbol	Parameter	$T_A = -40°C$ to $+85°C$, $V_{CC} = 4.5V$ to $5.5V$, $C_L = 50pF$, 8 Outputs Switching[6]			$T_A = -40°C$ to $+85°C$, $V_{CC} = 4.5V$ to $5.5V$, $C_L = 250pF$, 1 Output Switching[7]		$T_A = -40°C$ to $+85°C$, $V_{CC} = 4.5V$ to $5.5V$, $C_L = 250pF$, 8 Outputs Switching[8]		Units
		Min.	Typ.	Max.	Min.	Max.	Min.	Max.	
f_{TOGGLE}	Max Toggle Frequency		100						MHz
t_{PLH}	Propagation Delay	1.5		5.0	1.5	6.0	2.5	8.5	ns
t_{PHL}	Data to Outputs	1.5		5.0	1.5	6.0	2.5	8.5	
t_{PZH}	Output Enable Time	1.5		6.5	2.5	7.5	2.5	9.5	ns
t_{PZL}		1.5		6.5	2.5	7.5	2.5	11.0	
t_{PHZ}	Output Disable Time	1.0		6.5	(9)		(9)		ns
t_{PLZ}		1.0		5.6					

Notes:

6. This specification is guaranteed but not tested. The limits apply to propagation delays for all paths described switching in phase (i.e., all LOW-to-HIGH, HIGH-to-LOW, etc.).

7. This specification is guaranteed but not tested. The limits represent propagation delay with 250pF load capacitors in place of the 50pF load capacitors in the standard AC load. This specification pertains to single output switching only.

8. This specification is guaranteed but not tested. The limits represent propagation delays for all paths described switching in phase (i.e., all LOW-to-HIGH, HIGH-to-LOW, etc.) with 250pF load capacitors in place of the 50pF load capacitors in the standard AC load.

9. The 3-STATE delays are dominated by the RC network (500Ω, 250pF) on the output and have been excluded from the datasheet.

Skew

SOIC package.

Symbol	Parameter	$T_A = –40°C$ to $+85°C$, $V_{CC} = 4.5V$ to $5.5V$, $C_L = 50pF$, 8 Outputs Switching[12] Max.	$T_A = –40°C$ to $+85°C$, $V_{CC} = 4.5V$ to $5.5V$, $C_L = 250pF$, 8 Outputs Switching[13] Max.	Units
t_{OSHL}[10]	Pin to Pin Skew, HL Transitions	1.3	2.3	ns
t_{OSLH}[10]	Pin to Pin Skew, LH Transitions	1.0	1.8	ns
t_{PS}[14]	Duty Cycle, LH–HL Skew	2.0	3.5	ns
t_{OST}[10]	Pin to Pin Skew, LH/HL Transitions	2.0	3.5	ns
t_{PV}[11]	Device to Device Skew, LH/HL Transitions	2.0	3.5	ns

Notes:

10. Skew is defined as the absolute value of the difference between the actual propagation delays for any two separate outputs of the same device. The specification applies to any outputs switching HIGH-to-LOW (t_{OSHL}), LOW-to-HIGH (t_{OSLH}), or any combination switching LOW-to-HIGH and/or HIGH-to-LOW (t_{OST}). The specification is guaranteed but not tested.

11. Propagation delay variation for a given set of conditions (i.e., temperature and V_{CC}) from device to device. This specification is guaranteed but not tested.

12. This specification is guaranteed but not tested. The limits apply to propagation delays for all paths described switching in phase (i.e., all LOW-to-HIGH, HIGH-to-LOW, etc.)

13. These specifications guaranteed but not tested. The limits represent propagation delays with 250pF load capacitors in place of the 50pF load capacitors in the standard AC load.

14. This describes the difference between the delay of the LOW-to-HIGH and the HIGH-to-LOW transition on the same pin. It is measured across all the outputs (drivers) on the same chip, the worst (largest delta) number is the guaranteed specification. This specification is guaranteed but not tested.
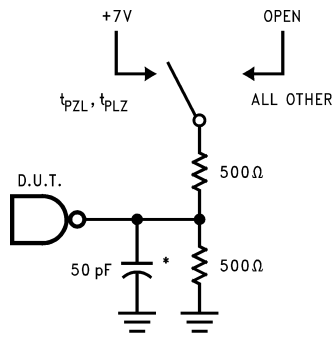
Capacitance

Symbol	Parameter	Conditions $T_A = 25°C$	Typ.	Units
C_{IN}	Input Capacitance	$V_{CC} = 0V$ ($\overline{OE}$, T/$\overline{R}$)	5.0	pF
$C_{I/O}$[15]	I/O Capacitance	$V_{CC} = 5.0V$ (A_n, B_n)	11.0	pF

Note:

15. $C_{I/O}$ is measured at frequency f = 1 MHz, per MIL-STD-883, Method 3012.

AC Loading

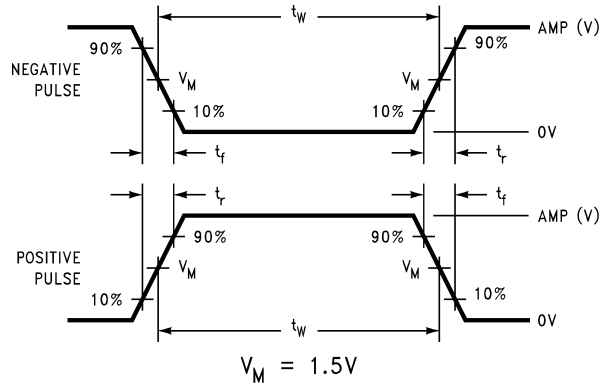*Includes jig and probe capacitance

Figure 1. Standard AC Test Load

$$V_M = 1.5V$$

Figure 2. Test Input Signal Levels

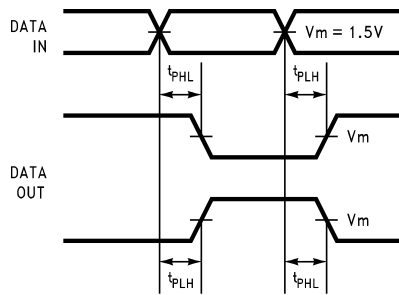| Amplitude	Rep. Rate	t_W	t_r	t_f
3.0V	1MHz	500ns	2.5ns	2.5ns

Figure 3. Test Input Signal Requirements

AC Waveforms

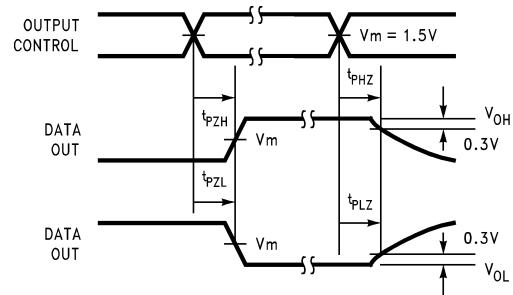**Figure 4. Propagation Delay Waveforms for Inverting and Non-Inverting Functions**
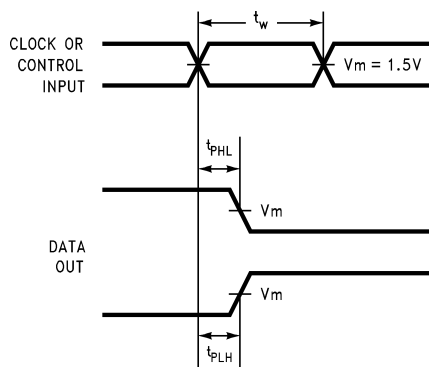

Figure 6. 3-STATE Output HIGH and LOW Enable and Disable Times

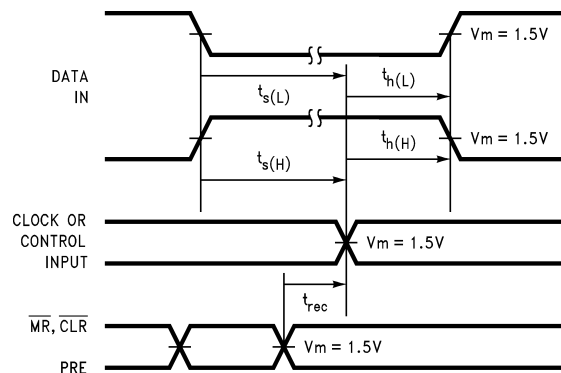**Figure 5. Propagation Delay, Pulse Width Waveforms**

Figure 7. Setup Time, Hold Time and Recovery Time Waveforms

Physical Dimensions
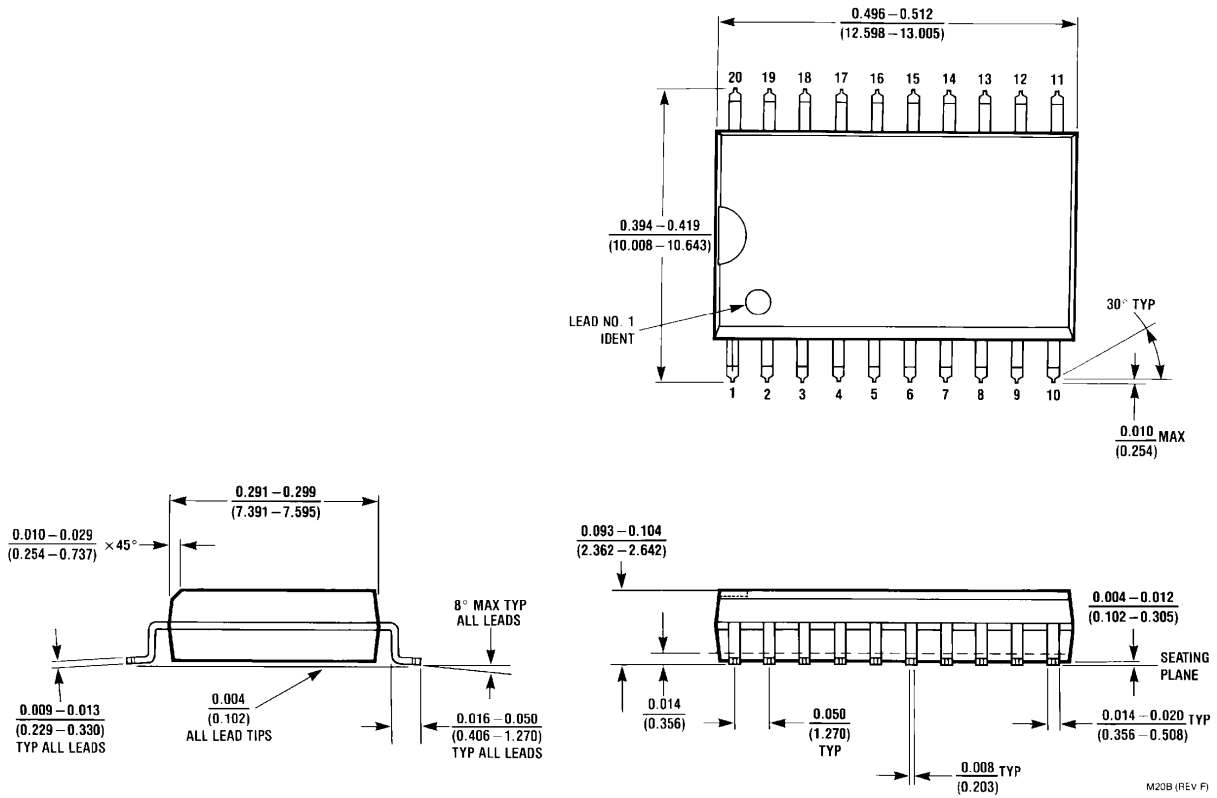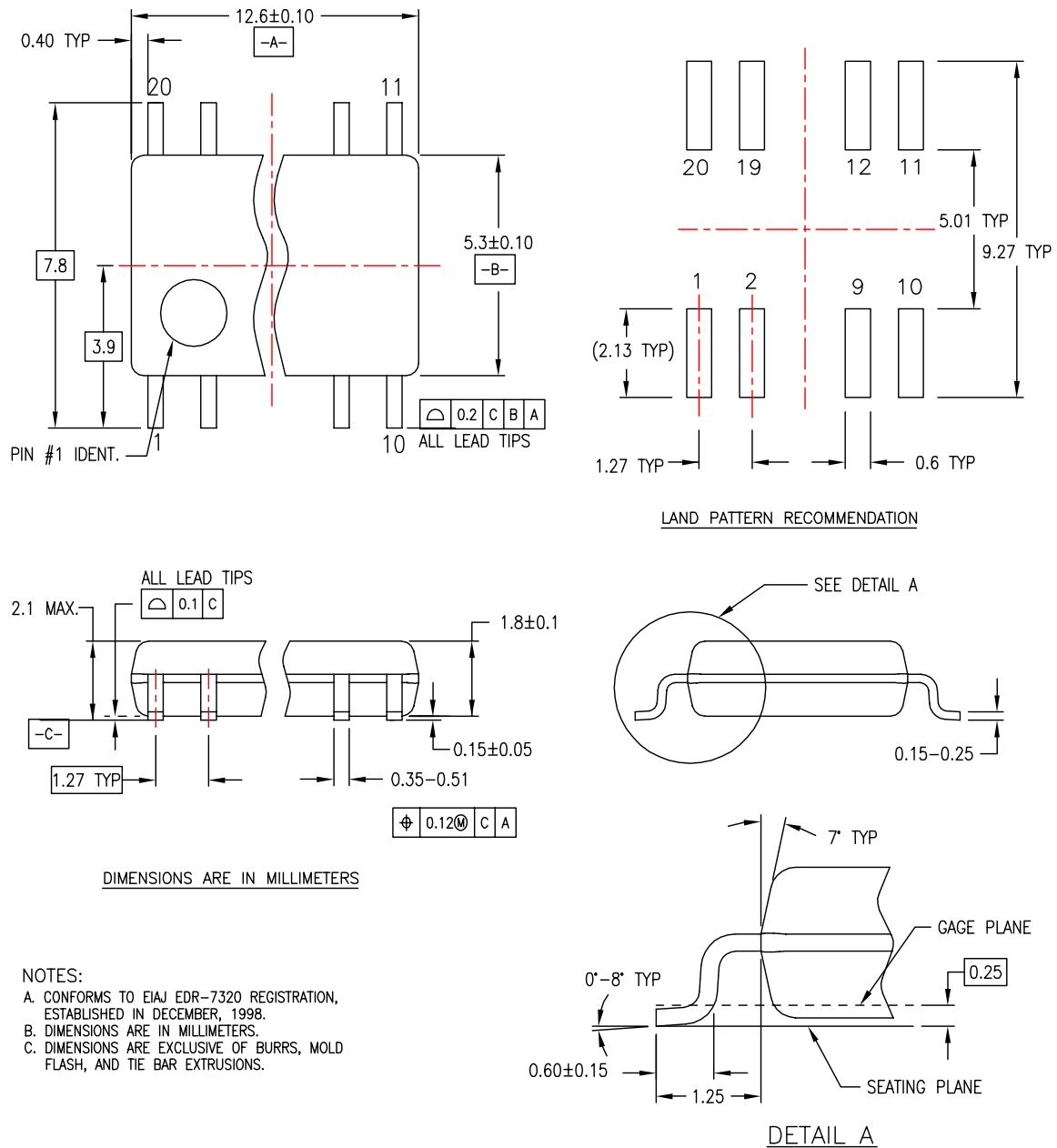Dimensions are in inches (millimeters) unless otherwise noted.

0.496 − 0.512
(12.598 − 13.005)

20 19 18 17 16 15 14 13 12 11

0.394 − 0.419
(10.008 − 10.643)

LEAD NO. 1
IDENT

1 2 3 4 5 6 7 8 9 10

30° TYP

0.010 MAX
(0.254)

0.291 − 0.299
(7.391 − 7.595)

0.010 − 0.029
(0.254 − 0.737) ×45°

8° MAX TYP
ALL LEADS

0.009 − 0.013
(0.229 − 0.330)
TYP ALL LEADS

0.004
(0.102)
ALL LEAD TIPS

0.016 − 0.050
(0.406 − 1.270)
TYP ALL LEADS

0.093 − 0.104
(2.362 − 2.642)

0.004 − 0.012
(0.102 − 0.305)

SEATING
PLANE

0.014
(0.356)

0.050
(1.270)
TYP

0.008 TYP
(0.203)

0.014 − 0.020 TYP
(0.356 − 0.508)

M20B (REV F)

Figure 8. 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
Package Number M20B

                                                                                                                           www.fairchildsemi.com

Physical Dimensions (Continued)
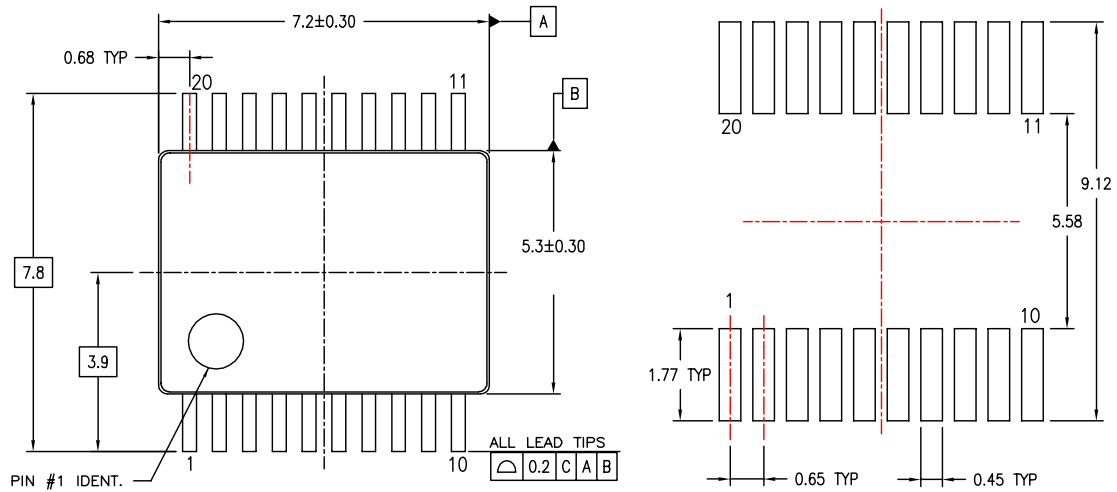
Dimensions are in millimeters unless otherwise noted.

74ABT245 Octal Bi-Directional Transceiver with 3-STATE Outputs

12.6±0.10
—A—
0.40 TYP
20
11
7.8
5.3±0.10
—B—
3.9
PIN #1 IDENT.
1
10
ALL LEAD TIPS
0.2 C B A

20 19 12 11
5.01 TYP
9.27 TYP
1 2 9 10
(2.13 TYP)
1.27 TYP
0.6 TYP

LAND PATTERN RECOMMENDATION

ALL LEAD TIPS
0.1 C
2.1 MAX.
—C—
1.27 TYP
1.8±0.1
0.15±0.05
0.35−0.51
0.12 M C A

DIMENSIONS ARE IN MILLIMETERS

SEE DETAIL A
0.15−0.25

7° TYP
GAGE PLANE
0.25
0°−8° TYP
0.60±0.15
1.25
SEATING PLANE
DETAIL A

NOTES:
A. CONFORMS TO EIAJ EDR−7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M20DREVC

Figure 9. 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M20D

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Physical Dimensions (Continued)
Dimensions are in millimeters unless otherwise noted.
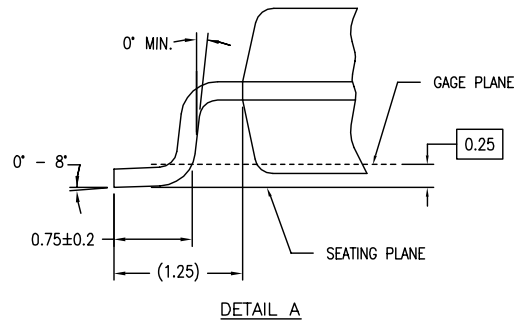

LAND PATTERN RECOMMENDATIONS
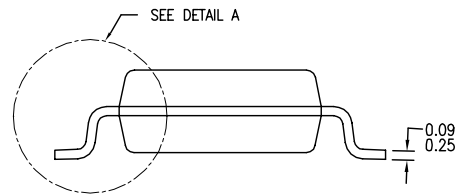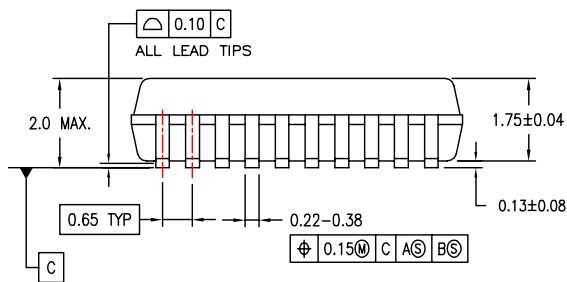
DIMENSIONS ARE IN MILLIMETERS

NOTES:
A. CONFORMS TO JEDEC REGISTRATION MO-150, VARIATION AE, DATE 1/94.
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
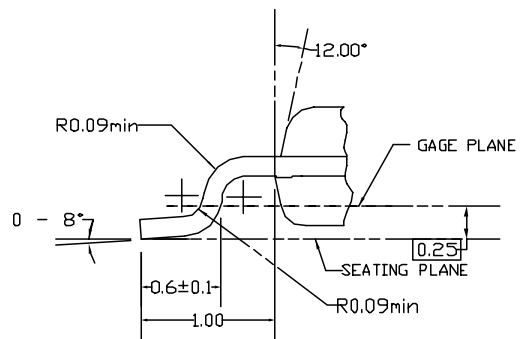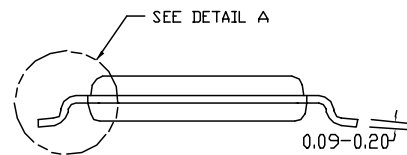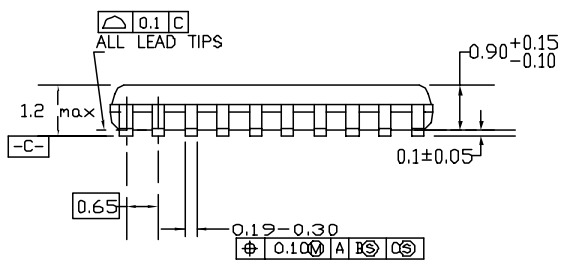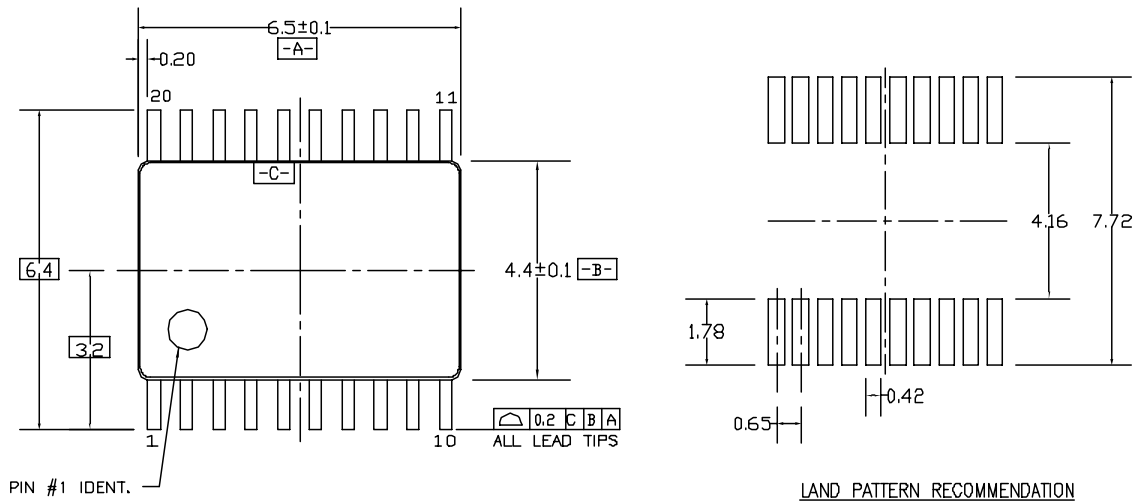D. DIMENSIONS AND TOLERANCES PER ASME Y14.5M – 1994.

DETAIL A

MSA20REVB

Figure 10. 20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide Package Number MSA20

Physical Dimensions (Continued)

Dimensions are in millimeters unless otherwise noted.

LAND PATTERN RECOMMENDATION

DIMENSIONS ARE IN MILLIMETERS

DETAIL A

NOTES:

A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AC, REF NOTE 6, DATE 7/93.

B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.

D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC20REVD1

Figure 11. 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC20

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Bottomless™	IntelliMAX™	QT Optoelectronics™	TinyWire™
Build it Now™	ISOPLANAR™	Quiet Series™	TruTranslation™
CoolFET™	MICROCOUPLER™	RapidConfigure™	μSerDes™
CROSSVOLT™	MicroPak™	RapidConnect™	UHC®
CTL™	MICROWIRE™	ScalarPump™	UniFET™
Current Transfer Logic™	MSX™	SMART START™	VCX™
DOME™	MSXPro™	SPM®	Wire™
E²CMOS™	OCX™	STEALTH™	
EcoSPARK®	OCXPro™	SuperFET™	
EnSigna™	OPTOLOGIC®	SuperSOT™-3	
FACT Quiet Series™	OPTOPLANAR®	SuperSOT™-6	
FACT®	PACMAN™	SuperSOT™-8	
FAST®	POP™	SyncFET™	
FASTr™	Power220®	TCM™	
FPS™	Power247®	The Power Franchise®	
FRFET®	PowerEdge™	™	
GlobalOptoisolator™	PowerSaver™	TinyBoost™	
GTO™	PowerTrench®	TinyBuck™	

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As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.

2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild Semiconductor. The datasheet is printed for reference information only.

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